# Gap Pad® VO Soft

Highly Conformable, Thermally Conductive Material for Filling Air Gaps

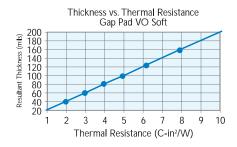
#### **Features and Benefits**

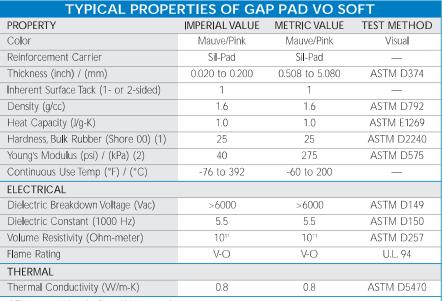
- Thermal conductivity: 0.8 W/m-K
- Conformable, low hardness
- Enhanced puncture, shear and tear resistance
- Electrically isolating



Gap Pad VO Soft is recommended for applications that require a minimum amount of pressure on components. Gap Pad VO Soft is a highly conformable, low-modulus, filled-silicone polymer on a rubber-coated fiberglass carrier. The material can be used as an interface where one side is in contact with a leaded device.

Note: Resultant thickness is defined as the final gap thickness of the application.





- 1) Thirty second delay value Shore 00 hardness scale.
- Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch? For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

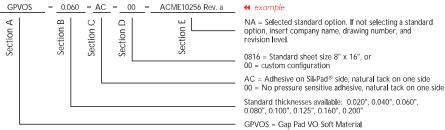
## **Typical Applications Include:**

- Telecommunications
- Computer and peripherals
- Power conversion
- Between heat-generating semiconductors or magnetic components and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader

## **Configurations Available:**

• Sheet form and die-cut parts

#### **Building a Part Number**



Standard Options

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad\*: U.S. Patent 5,679,457 and others

